[ABSTRACT]

According to one aspect of the technique of the present disclosure, there is provided a substrate processing apparatus including a nozzle arranged along an inner wall surface of a process vessel and provided at least in a lower portion of the process vessel with a gap between the nozzle and the inner wall surface of the process vessel; a nozzle base supporting the nozzle and accommodating therein a flow path communicating with the nozzle; a support structure provided along the inner wall surface and joined to a first joint surface of the nozzle base that does not face the inner wall surface; and a tilt-adjusting structure for adjusting a tilt of the nozzle base at a position shifted toward a center of the process vessel and away from a center of gravity of a nozzle assembly comprising the nozzle and the nozzle base.